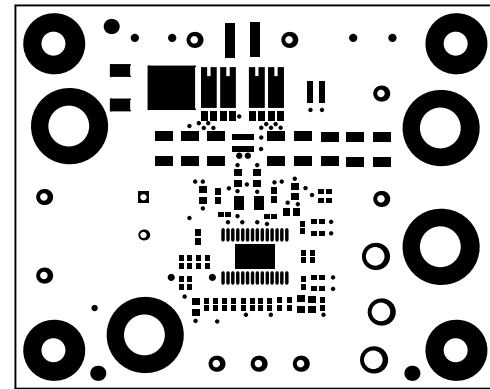
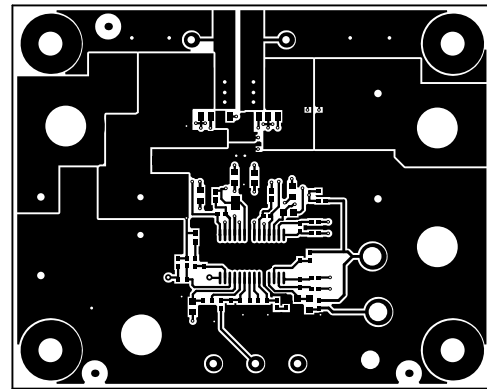


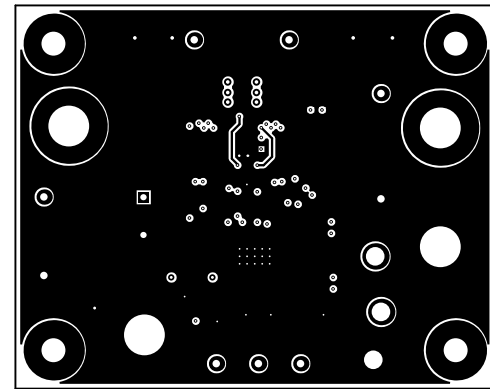
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10708	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: PMP10708		
PLOT NAME = Top Overlay	GENERATED : 9/2/2015	12:22:47 PM	TEXAS INSTRUMENTS



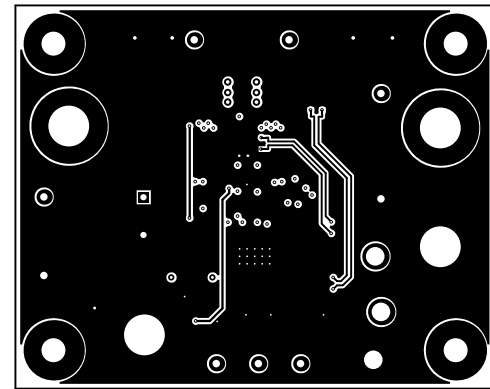
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10708	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: PMP10708		
PLOT NAME = Top Solder Mask	GENERATED : 9/2/2015 12:22:47 PM	TEXAS INSTRUMENTS	



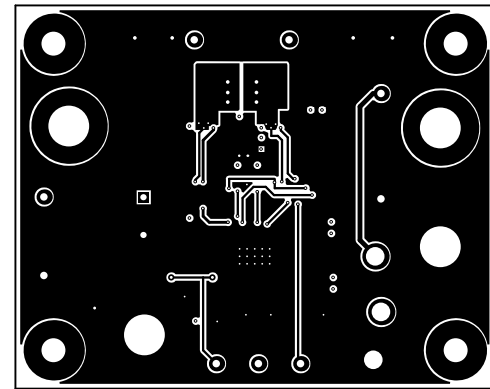
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10708	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP10708		
PLOT NAME = Top Layer	GENERATED : 9/2/2015 12:22:48 PM	TEXAS INSTRUMENTS	



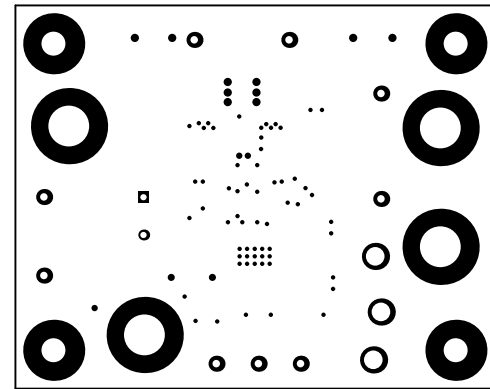
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10708	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP10708		
PLOT NAME = Signal Layer 1	GENERATED : 9/2/2015 12:22:49 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10708	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP10708		
PLOT NAME = Signal Layer 2	GENERATED : 9/2/2015 12:22:50 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10708	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP10708		
PLOT NAME = Bottom Layer	GENERATED : 9/2/2015 12:22:50 PM	TEXAS INSTRUMENTS	

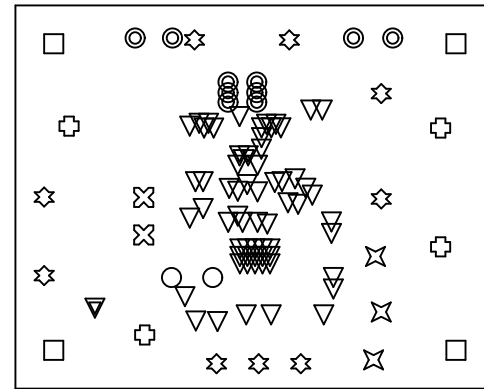


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10708	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP10708		
PLOT NAME = Bottom Solder Mask	GENERATED : 9/2/2015 12:22:51 PM	TEXAS INSTRUMENTS	



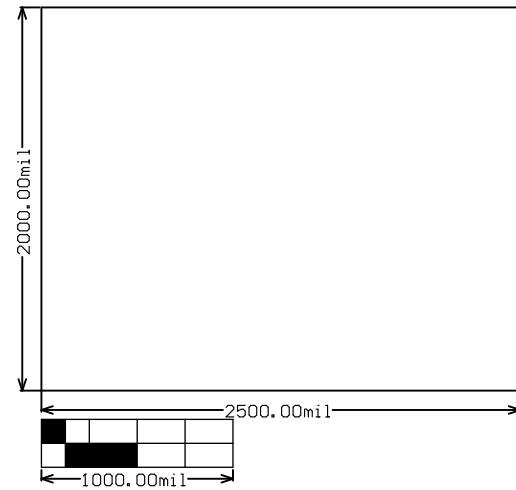
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10708	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: PMP10708		
PLOT NAME = Bottom Overlay	GENERATED : 9/2/2015 12:22:52 PM	TEXAS INSTRUMENTS	





Symbol	Quantity	Finished Hole Size	Plated	Hole Type
▽	62	10.00mil (0.254mm)	PTH	Round
▽	3	15.00mil (0.381mm)	PTH	Round
○	2	16.00mil (0.406mm)	PTH	Round
●	10	20.00mil (0.508mm)	PTH	Round
⊗	2	33.46mil (0.850mm)	PTH	Round
⊛	9	40.00mil (1.016mm)	PTH	Round
⊗	3	98.43mil (2.500mm)	PTH	Round
□	4	125.98mil (3.200mm)	PTH	Round
⊙	4	214.57mil (5.450mm)	PTH	Round
	99 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10708	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP10708		
PLOT NAME = Drill Drawing	GENERATED : 9/2/2015	12:22:53 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10708	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP10708		
PLOT NAME = Board Dimensions	GENERATED : 9/2/2015 12:22:54 PM	TEXAS INSTRUMENTS	

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